

General Description

The Sanrise SRC60R100B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R100B break down voltage is 600V and it has a high rugged avalanche characteristics. The SRC60R100B is available in TO-263-2, TO-247 packages.

Features

- Ultra Low $R_{DS(ON)} = 100m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 86nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Qualified according to AEC Q101
- Green Product (RoHS compliant)
- Ultra-fast body diode

Application

- On-Board Charger
- DC/DC Converter
- Auxiliary Inverter

Symbol

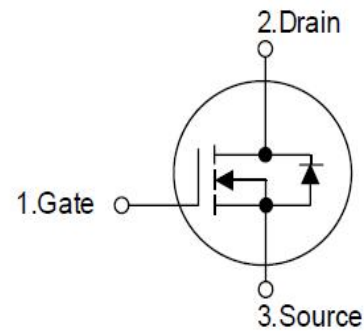
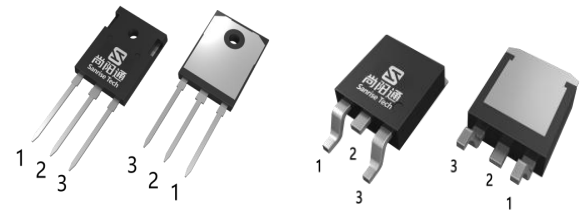


Figure 1 Symbol of SRC60R100B

Package Type

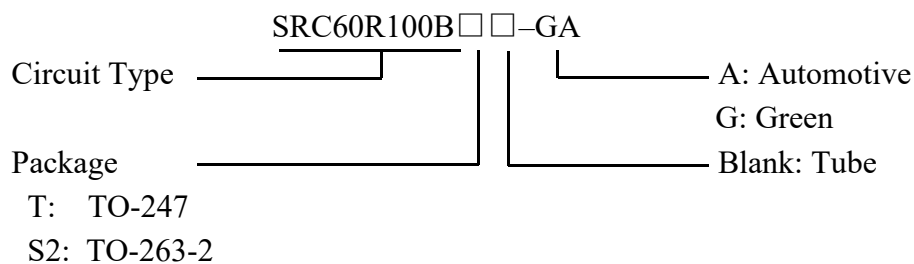


TO-247

TO-263-2

Figure 2 Package Types of SRC60R100B

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-247	SRC60R100BT-GA	SRC60R100BTGA	Tube
TO-263-2	SRC60R100BS2TR-GA	SRC60R100BS2GA	Tape & Reel

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	600	V
Gate-Source Voltage (static)		V_{GSS}	±20	V
Gate-Source Voltage (dynamic), AC ($f > 1$ Hz)			±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	36.9	A
	$T_C = 100^\circ\text{C}$		23.3	
	$T_C = 125^\circ\text{C}$		16.5	
Pulsed Drain Current (Note 2)		I_{DM}	110.7	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	135	mJ
Avalanche Energy, Single Pulse (Note 4)		E_{AS}	1020	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.6	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	4.5	A
Continuous Diode Forward Current		I_S	36.9	A
Diode Pulse Current		$I_{S,PULSE}$	110.7	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt , $V_{DS} \leq 480\text{V}$, $I_{SD} \leq I_D$		dv/dt	50	V/ns
Power Dissipation (TO-263-2, TO-247)		P_{tot}	291	W
Operating Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS} = 2.0\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Finish goods test condition.
4. $I_{AS} = 5.5\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Typical E_{AS} .

Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-247	R_{thJC}			0.43	$^\circ\text{C}/\text{W}$
	TO-263-2				0.43	
Thermal resistance, Junction-to-Ambient	TO-247	R_{thJA}			58	$^\circ\text{C}/\text{W}$
	TO-263-2				58	

Electrical Characteristics

$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			10	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=800\mu A$	3.0	4.0	5.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=18A$		82	100	mΩ
Gate Resistance	R_G	f=1MHz, Open Drain		0.7		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		3333		pF
Output Capacitance	C_{OSS}			3466		
Reverse Transfer Capacitance	C_{RSS}			46.9		
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		98.2		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			601		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=18A, R_G=1.8\Omega, V_{GS}=10V$		24		ns
Rise Time	t_r			38		
Turn-off Delay Time	$t_{d(off)}$			48		
Fall Time	t_f			10		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=18A, V_{GS}=0 \text{ to } 10V$		22.9		nC
Gate to Drain Charge	Q_{gd}			42.6		
Gate Charge Total	Q_g			86		
Gate Plateau Voltage	$V_{plateau}$			6.5		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=18A$		0.9	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=100V, I_F=18A, dI_F/dt=100A/\mu s$		152		ns
Reverse Recovery Charge	Q_{rr}			0.89		μC
Peak Reverse Recovery Current	I_{rrm}			11.6		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V

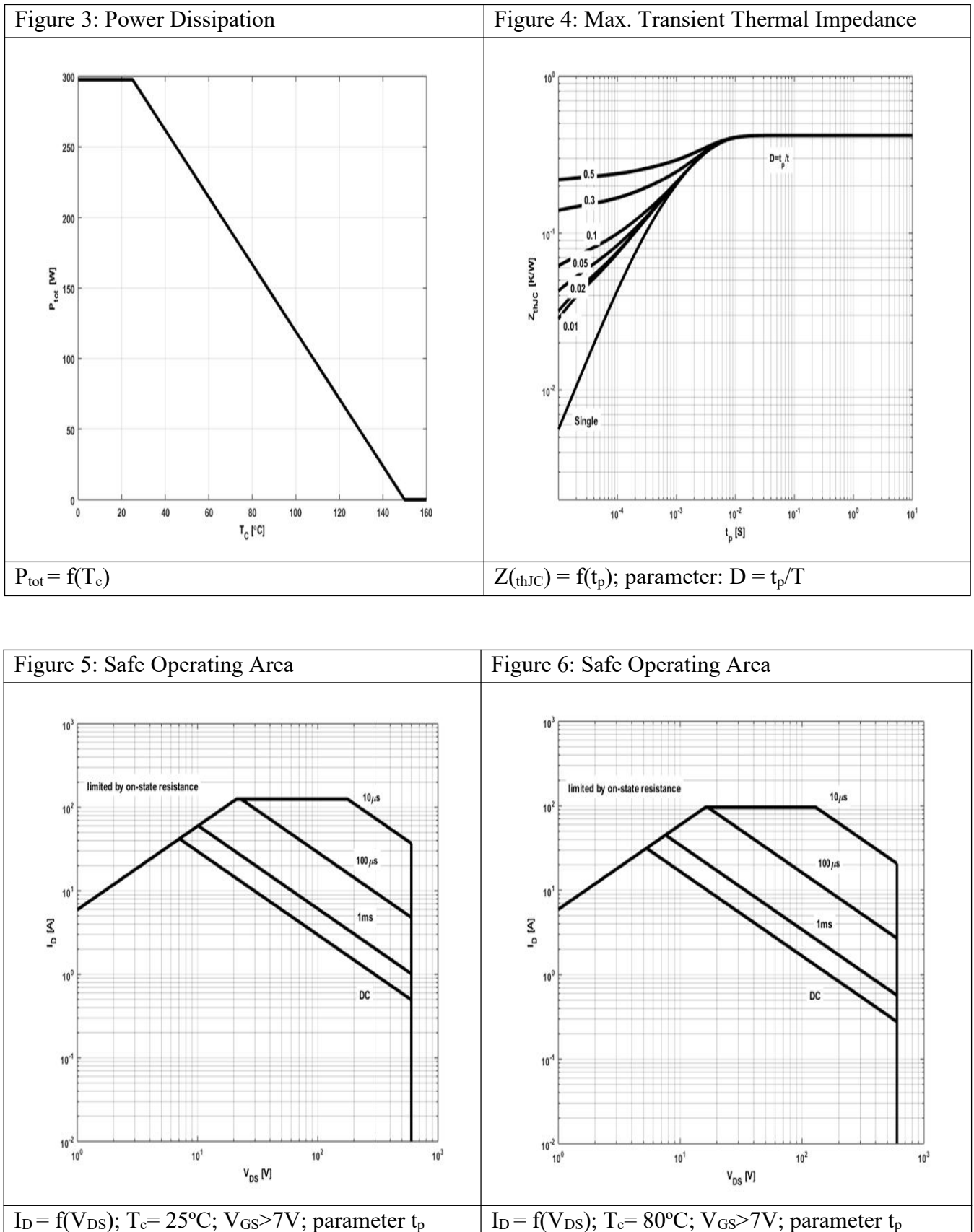
Typical Performance Characteristics


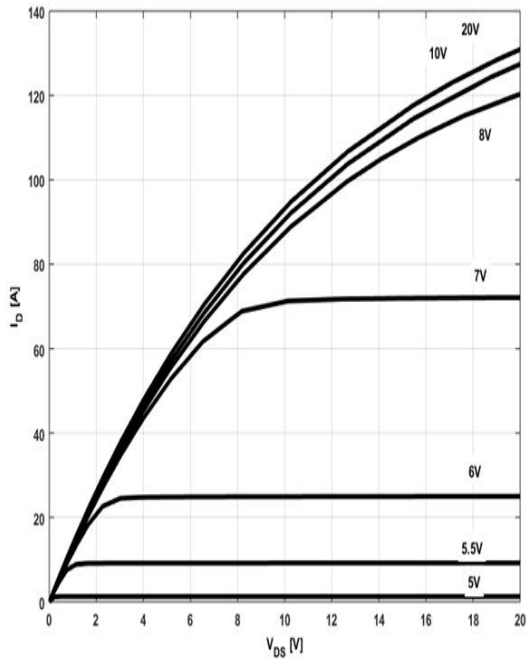
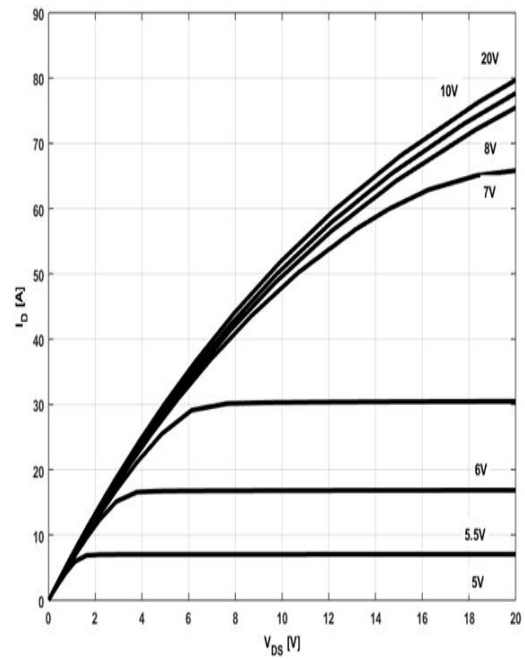
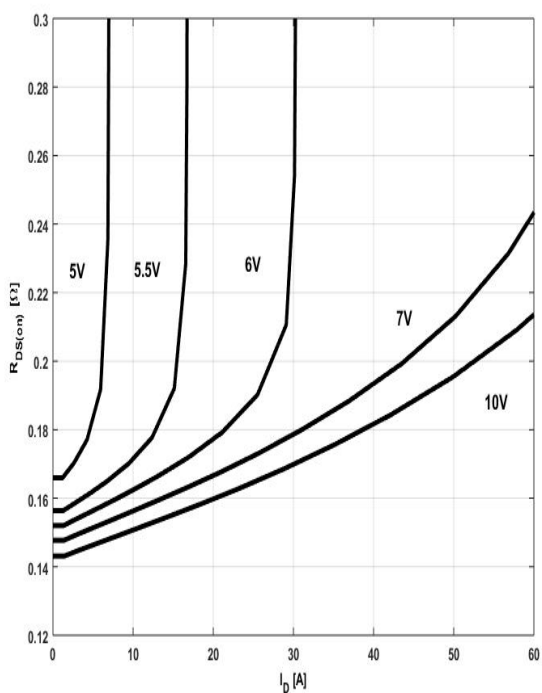
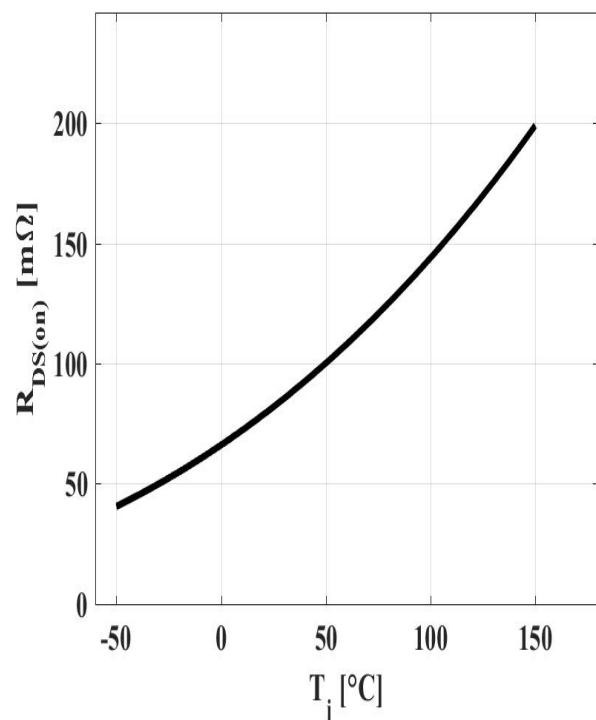
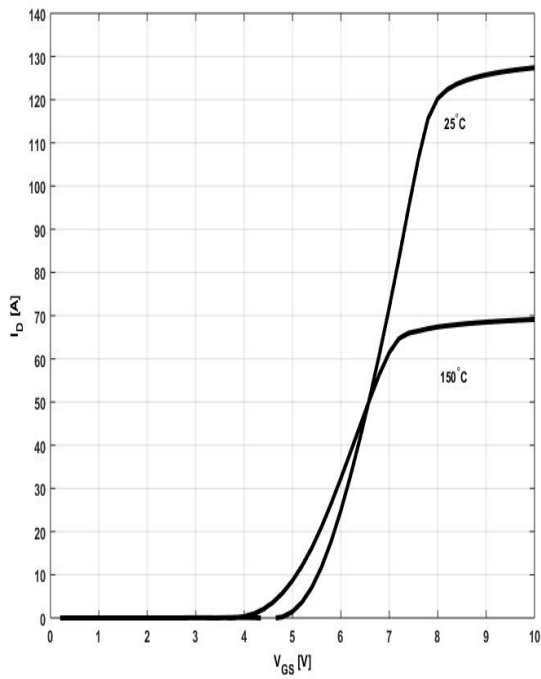
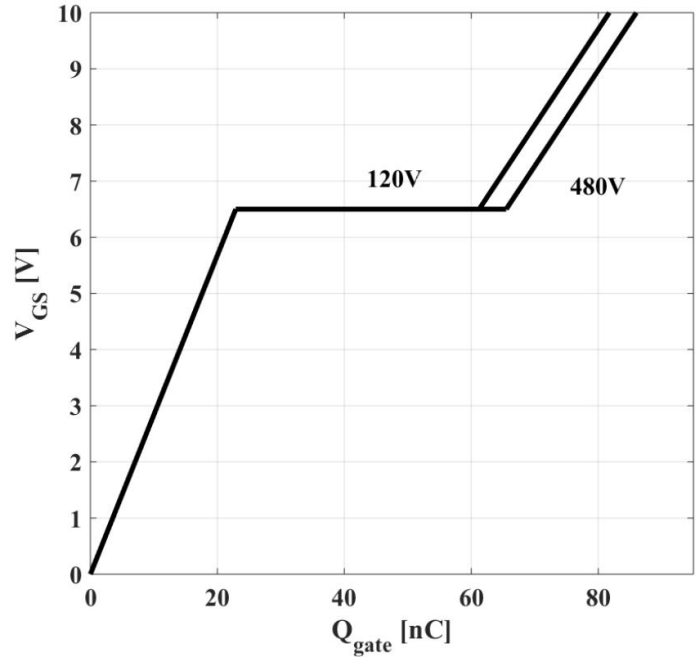
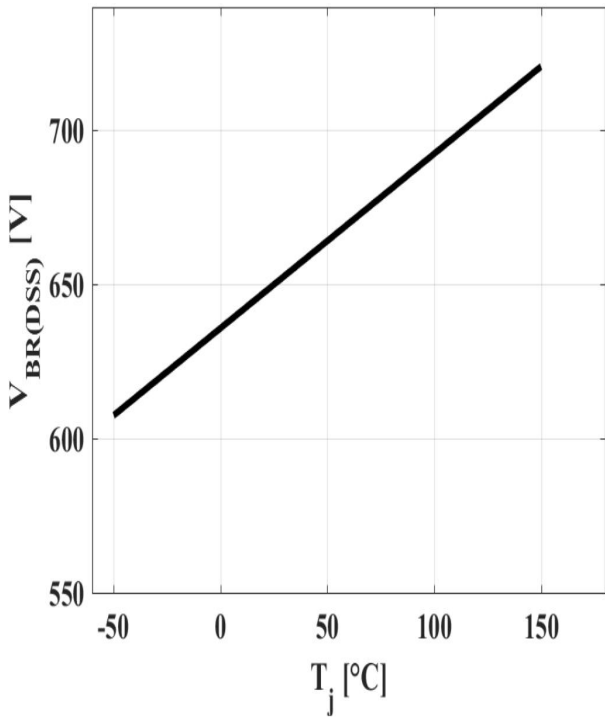
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 18\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics


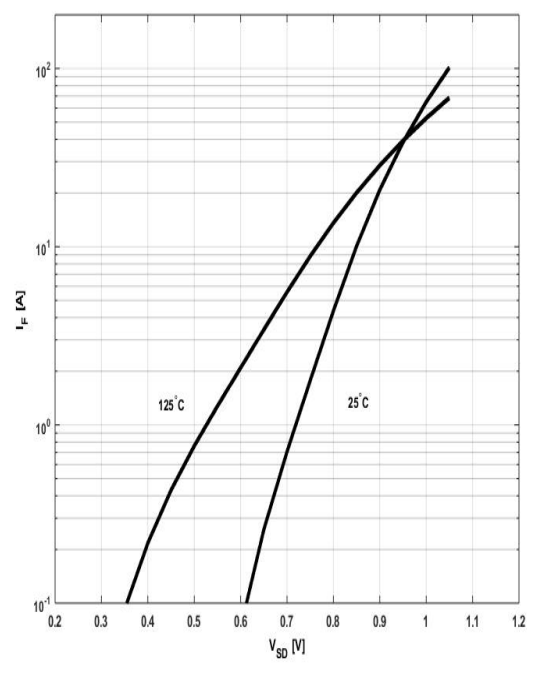
$$I_D = f(V_{GS}); V_{DS} = 20V$$

Figure 12: Typ. Gate Charge


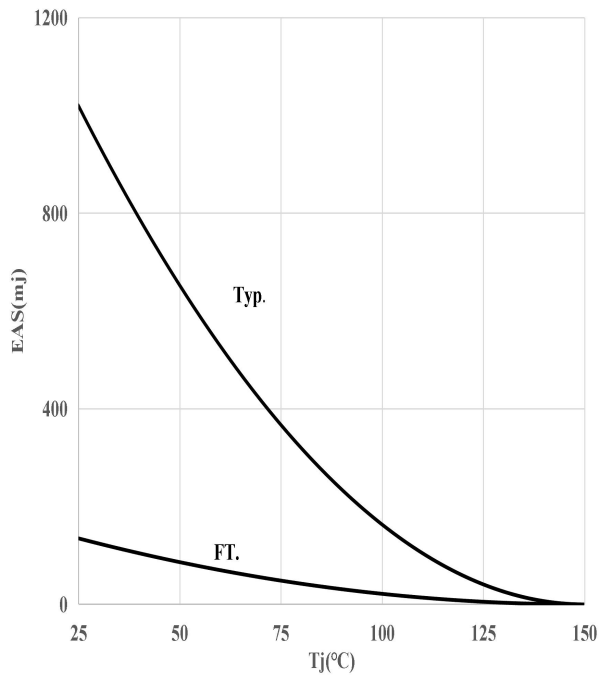
$$V_{GS} = f(Q_{gate}), I_D = 18A \text{ pulsed}$$

Figure 13: Drain-Source Breakdown Voltage


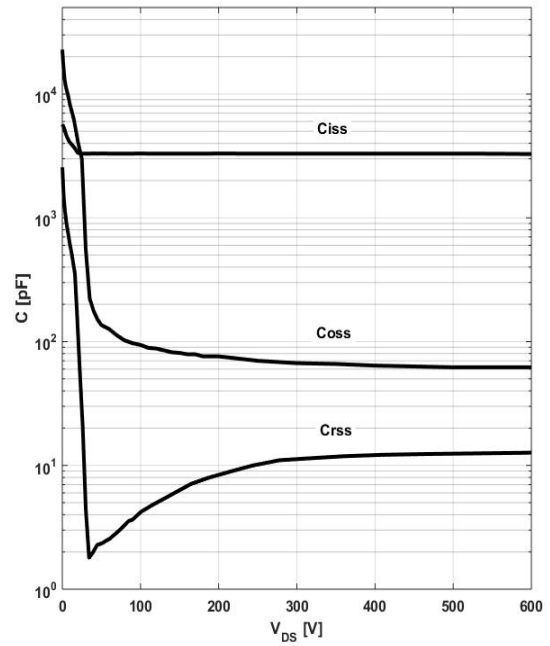
$$V_{BR(DSS)} = f(T_j); I_D = 10mA$$

Figure 14: Forward Characteristics of Reverse Diode


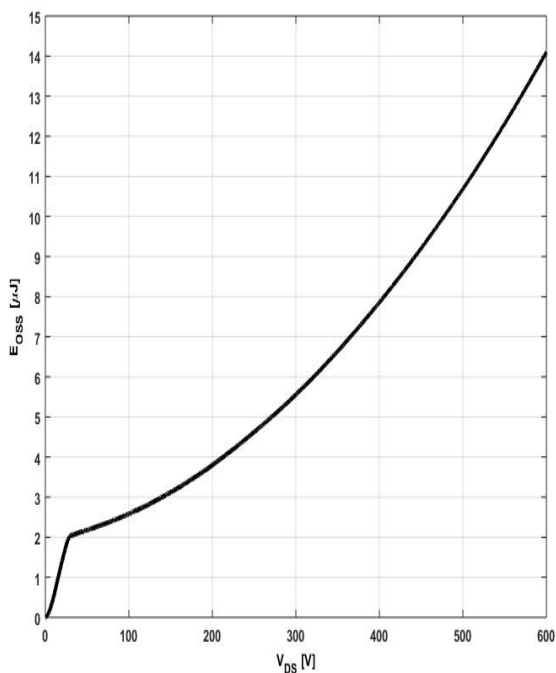
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

Figure 15: Avalanche Energy


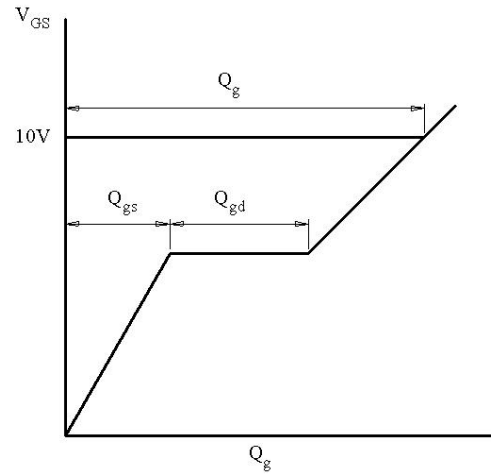
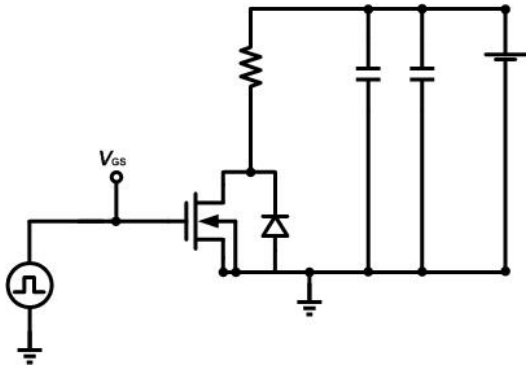
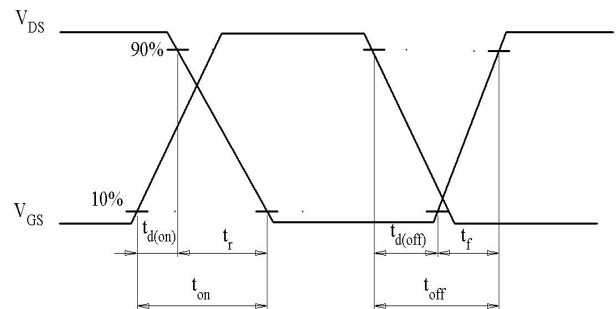
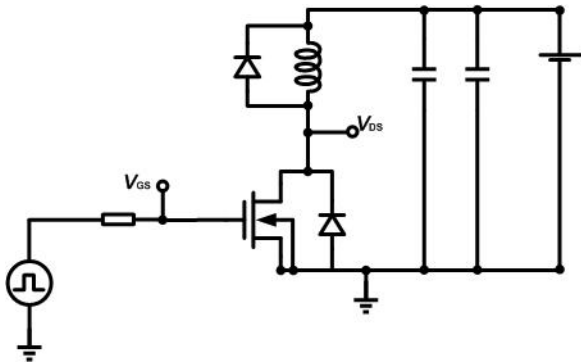
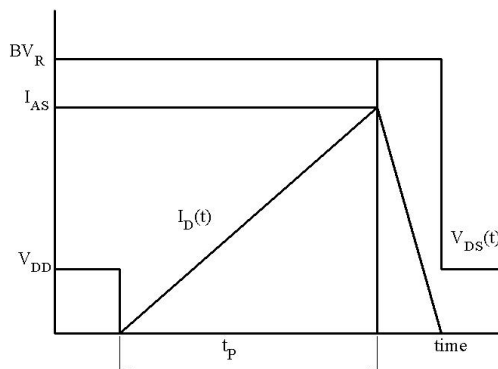
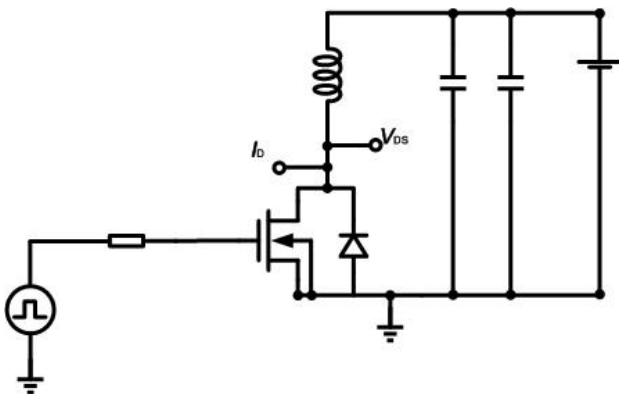
$$E_{AS}=f(T_j); V_{DD}=60V$$

Figure 16: Typ. Capacitances


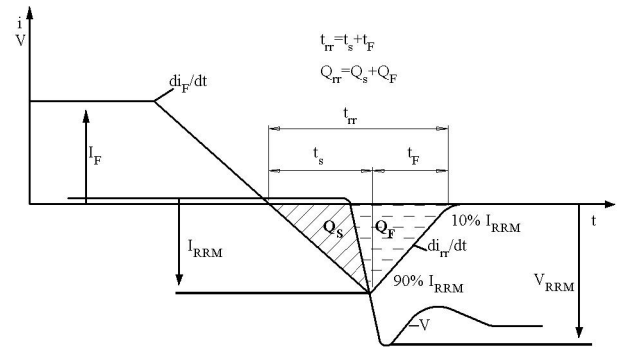
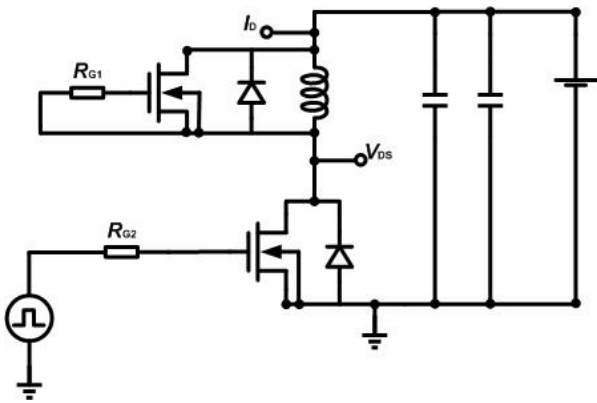
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

Figure 17: Coss Stored Energy


$$E_{OSS}=f(V_{DS})$$

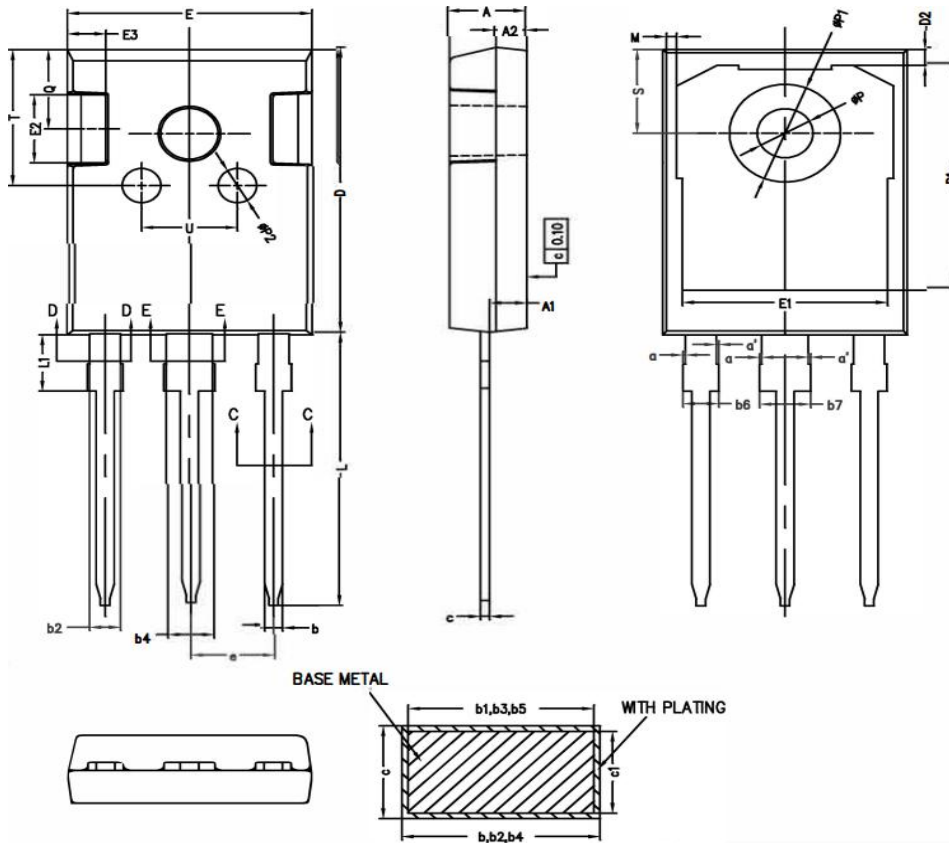
Test Circuits
1. Gate Charge Test Circuit & Waveform

2. Switch Time Test Circuit

3. Unclaimed Inductive Switching Test Circuit & Waveforms


4. Test Circuit and Waveform for Diode Characteristics



Mechanical Dimensions
TO-247(Package 1)

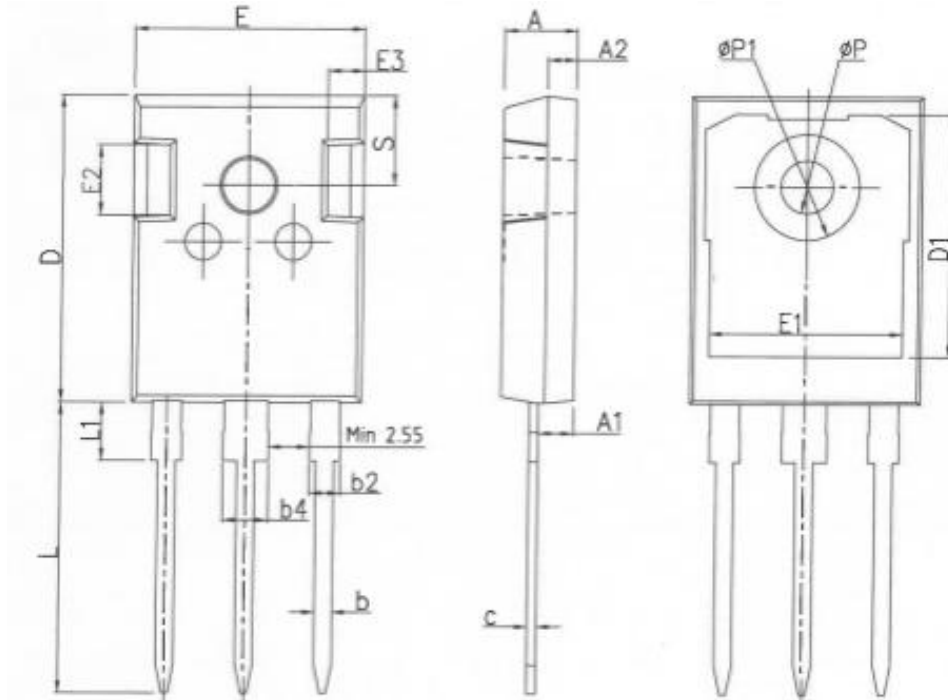
Unit: mm



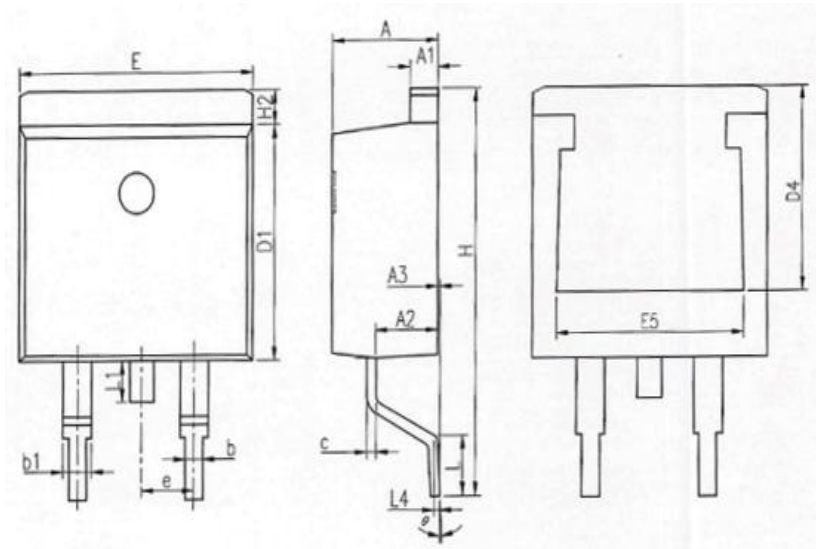
Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.90	5.00	5.10	E2	4.90	5.00	5.10
A1	2.31	2.41	2.51	E3	2.40	2.50	2.60
A2	1.90	2.00	2.10	e	5.34	5.44	5.54
b	1.12	-	1.22	L	19.80	19.92	20.10
b1	1.11	1.16	1.18	L1	3.95	4.13	4.30
b2	1.96	-	2.06	P	3.50	3.60	3.70
c	0.59	-	0.66	P1	7.00	-	7.40
D	20.90	21.00	21.10	P2	2.40	2.50	2.60
D1	16.25	16.55	16.85	Q	5.60	-	6.00
D2	1.05	1.20	1.35	S	6.05	6.15	6.25
E	15.70	15.80	15.90	T	9.80	-	10.20
E1	13.10	13.30	13.50	U	6.00	-	6.40
b3	1.95	2.00	2.02	b6	-	-	2.25
b4	2.96	-	3.06	b7	-	-	3.25
b5	2.95	3.00	3.02	c1	0.58	0.60	0.62
M	0.35	-	0.95	a	0	-	0.15
a'	0	-	0.15				

Mechanical Dimensions
TO-247(Package 2)

Unit: mm



Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E	15.50	15.80	16.10
A1	2.21	2.41	2.59	E1	13.00	13.30	13.60
A2	1.85	2.00	2.15	E2	4.80	5.00	5.20
b	1.11	1.21	1.36	E3	2.30	2.50	2.70
b2	1.91	2.01	2.21	e	5.44BSC		
b4	2.91	3.01	3.21	M	0.35	-	0.95
c	0.51	0.61	0.75	a'	0	-	0.15
D	20.70	21.00	21.30	L	19.62	19.92	20.22
D1	16.25	16.55	16.85	L1	-	-	4.30
ϕP	3.40	3.60	3.80	S	6.15BSC		
$\phi P1$	-	-	7.30				

Mechanical Dimension
TO-263-2
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0.00	0.13	0.25
b	0.70	0.81	0.96
b1	1.17	1.27	1.47
c	0.30	0.38	0.53
D1	8.50	8.70	8.90
D4	6.60	-	-
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54(BSC)		
H	14.70	15.10	15.50
H2	1.07	1.27	1.47
L	2.00	2.30	2.60
L1	1.40	1.55	1.70
L4	0.25(BSC)		
θ	0°	5°	8°



Shenzhen Sanrise Technology Co., LTD

<http://www.sanrise-tech.com>

IMPORTANT NOTICE

Shenzhen Sanrise Technology Co., LTD reserves the right to make changes without further notice to any products or specifications herein. Shenzhen Sanrise Technology Co., LTD does not assume any responsibility for use of any its products for any particular purpose, nor does Shenzhen Sanrise Technology Co., LTD assume any liability arising out of the application or use of any its products or circuits. Shenzhen Sanrise Technology Co., LTD does not convey any license under its patent rights or other rights nor the rights of others.

Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaoxinnan 1st Road,
Gaoxin District, Yuehai street,, Nanshan District, ShenZhen,
P.R.China
Tel: +86-755-22953335
Fax: +86-755-22916878

- Shanghai Office

Shenzhen Sanrise Technology Co., LTD.
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China
Tel: +86-21-68825918